

ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF MANUFACTURING THE SAME

Abstract

There are included a wiring substrate including a predetermined wiring pattern, an electronic parts connection terminal on an element forming surface of which is flip-chip connected to the wiring pattern, an insulating film for covering the electronic parts, a via hole formed in a predetermined portion of the electronic parts and the insulating film on the connection terminal, and an overlying wiring pattern formed on the insulating film and connected to the connection terminal via the via hole.